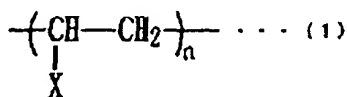


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5. The multilayer printed circuit board according to Claim 1 wherein said polyolefin resin is a resin which has a repeating unit represented by the following chemical formula (1) and contains a double bond, an oxide structure, a lactone structure or a mono- or polycyclopentadiene structure in its backbone chain.



wherein n represents 1 to 10000; X represents a hydrogen atom, an alkyl group, a phenyl group, a hydroxyl group, an unsaturated hydrocarbon residue having 2 to 3 carbon atoms, an oxide group or a lactone group.

6. A multilayer printed circuit board wherein the polyolefin resin is a mixed resin of two or more species of the polyolefin resin according to Claim 4, a resin composed of two or more polyolefin resin crosslinked to one another according to Claim 4, or a mixed resin comprising a polyolefin resin selected from the polyolefin resin according to Claim 4 and a thermosetting resin.

7. The multilayer printed circuit board according to Claim 1 wherein said conductor circuit is constructed on the resin insulating layer by way of a metal layer composed of at least one metal selected from among the metals (exclusive of Cu) of the 4<sup>th</sup> to 7<sup>th</sup> periods in Group 4A through Group 1B of the long-form periodic table of the elements, Al and Sn.

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8. The multilayer printed circuit board according to Claim 1 wherein said metal layer is disposed on a flat and level resin insulating layer.

9. The multilayer printed circuit board according to Claim 1 wherein said resin insulating layer has a surface obtained by plasma treatment or corona discharge treatment.

10. The multilayer printed circuit board according to Claim 1 wherein said substrate board is a board carrying the conductor circuit on its surface or inside.

13. The multilayer printed circuit board according to Claim 11 wherein said cycloolefin resin is a homopolymer or copolymer of 2-norbornene, 5-ethylidene-2-norbornene and/or any of their derivatives.

14. The multilayer printed circuit board according to Claim 11 wherein said cycloolefin resin is a thermosetting cycloolefin resin.

42. The process for constructing a conductor circuit according to Claim 38 wherein said acid etching solution is an aqueous solution of sulfuric acid, an aqueous solution of hydrogen chloride or an aqueous mixed solution of sulfuric acid and hydrogen peroxide.

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47. The process for manufacturing a multilayer printed circuit board according to Claim 43 wherein said acid etching solution is an aqueous solution of sulfuric acid, an aqueous solution of hydrogen chloride or an aqueous mixed solution of sulfuric acid and hydrogen peroxide.

50. The method of forming a metal film according to Claim 48 wherein the concentration of said reducing acid solution is 4.0 to 8.0 mol/L.

53. The process for manufacturing a multilayer printed circuit board according to Claim 51 wherein the concentration of said aqueous reducing acid solution is 4.0 to 8.0 mol/L.